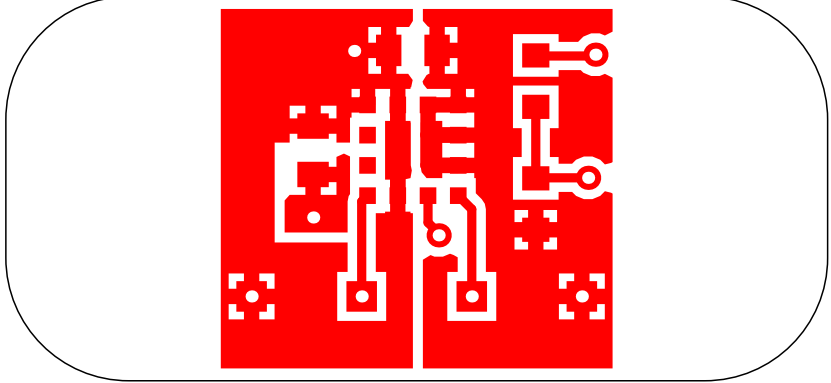
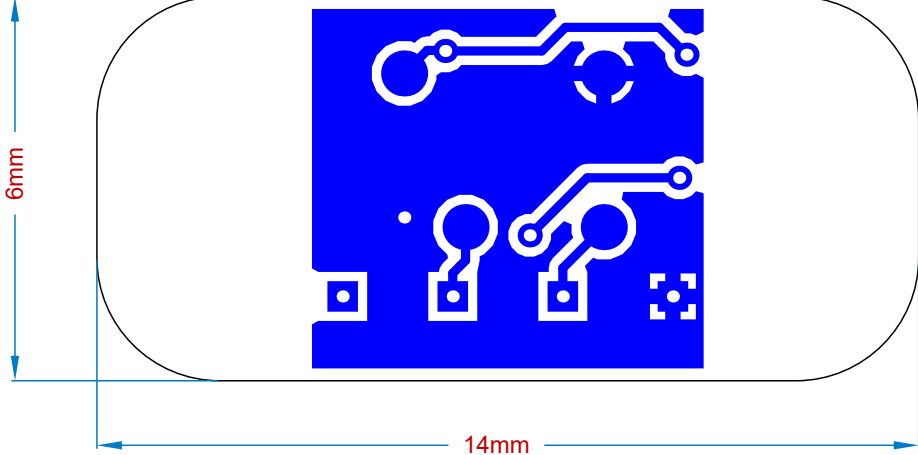


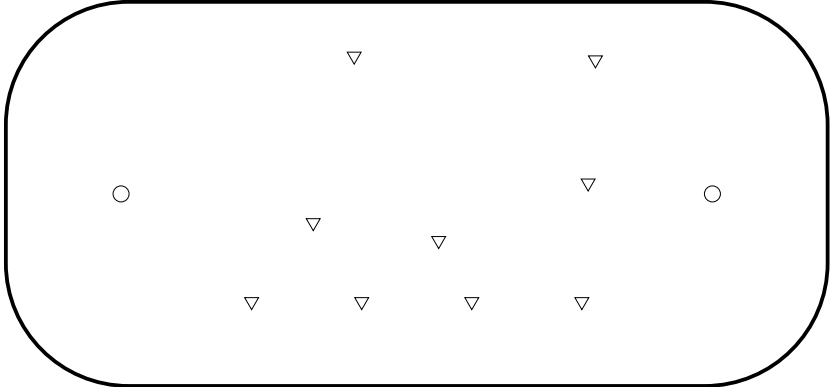
Top Layer (Scale 8:1)



Bottom Layer (Scale 8:1)



Drill Drawing View (Scale 8:1)



Drill Table

Symbol	Count	Hole Size	Plated
▽	9	8mil	Plated
○	2	98mil	Non-Plated
	11 Total		

Notes

- Board material is Polyimide.
- Manufacture to IPC-6012A Class 2 quality level.
- Minimum trace width/spacing is 6mil.
- Surface finish must be ENIG (Electroless Nickel Immersion Gold).
 - Electroless nickel thickness: 3 - 6um (refer to IPC-4552).
 - Immersion gold thickness: 0.05um minimum.
- Silkscreen (overlay) is white on both sides.
- Soldermask is green.
- All vias should be tented.

Layer Stack

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	1mil	SM-001	Solder Mask	GTS
Lead-Free	Top Surface Finish	1mil		Surface Finish	
CF-004	Top Layer	1mil		Signal	GTL
Core		2mil	Core-001	Dielectric	
CF-004	Bottom Layer	1mil		Signal	GBL
Lead-Free	Bottom Surface Finish	1mil		Surface Finish	
Surface Material	Bottom Solder	1mil	SM-001	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 8mil					

	Project: XLBoard.PrjPcb	
	Schematic: Draftsman	Ver: 1.1
	Design by: M. Ferreira	Date: 17/07/2025
	Reviewed by: J. Evia	Sheet: 1 / 1